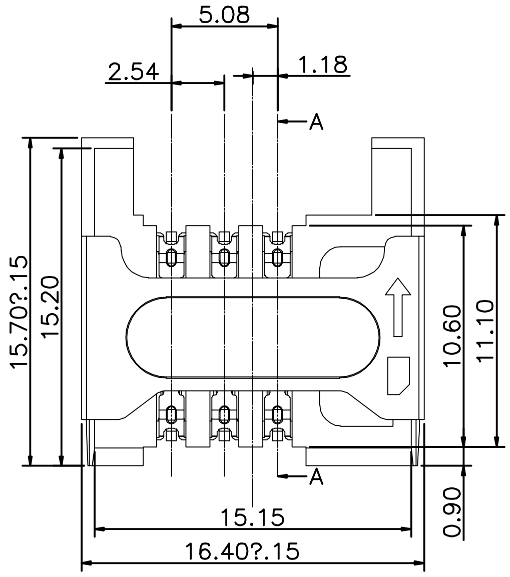
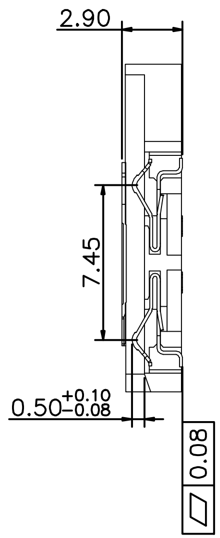
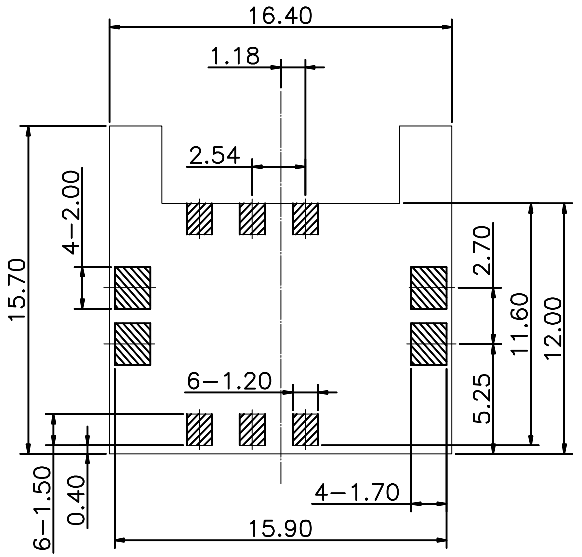
| REV. | ECN.NO. | MODIFY.CONTENT | DATE |
|---|---|---|---|
| A |  | NEW | 2011/10/31 |



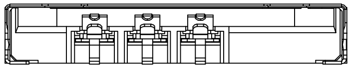


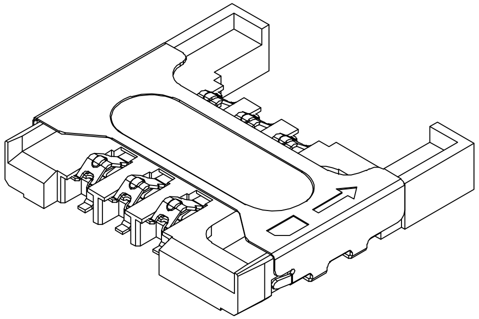
SECTION A–A

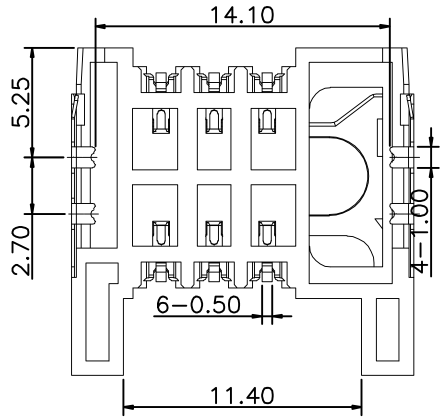


RECOMMENDED PCB LAYOUT

TOL:(±0.05)







**NOTES:**

1. **MATERIAL:**
   - **HOUSING: LCP, GLASS FILLED, UL94V-0**
   - **CONTACT: PHOSPHOR BRONZE, T=0.15mm**
   - **SHELL: STAINLESS STEEL, T=0.15mm**
2. **FINISH:**
   - **CONTACT: 40-150u" UNDER PLATING ALL OVER GOLD FLASH 1u" MIN ALL OVER**
   - **SHELL: SELECTIVE GOLD FLASH IN SOLDER TAIL AREA UNDERPLATING 40-150u" NICKEL OVERALL**

| GENERAL TOLERANCE |  | DWG NO. | MRK-SM03-280-0012 | APPD: | WIND | Scale | 1:1 |
|---|---|---|---|---|---|---|---|
| X.±0.45 | x.°±5° | Title | SIM CARD 6P 2.8H<br>连桥 有档 | CHKD: |  | UNIT | mm |
| .X±0.35 | .x°±2° |  |  | DR: |  |  |  |
| .XX±0.25 | .xx°±1° | Part NO. |  | Date | 2013/02/29 |  |  |
| .XXX±0.15 | .xxx°±0.5° |  | 深圳市迈睿康科技有限公司 |  |  |  |  |
| SHEET 1/1 |  |  |  |  |  |  |  |